

1) (Currently Amended) An improved process for manufacture and assembly of a plurality of adjoined printed ~~wiring~~ circuit boards, comprising:

(a) forming at least a first circuit pattern and a second circuit pattern on a common printed circuit board substrate;

(b) fastening at least one electrically conductive pre-formed wire to connect at least the first circuit pattern to the second circuit pattern;

(c) separating the common printed circuit board substrate into at least a first substrate and a second substrate with the first substrate including the first circuit pattern thereon and the second substrate including the second circuit pattern thereon; and

(d) tilting the first substrate relative to the second substrate while maintaining the connection between the first circuit pattern and the second circuit pattern.

2) (Previously Presented) The process of **claim 1**, further comprising scoring the common circuit board substrate along a dividing line.

3) (Previously Presented) The process of **claim 1**, further comprising holding the separated substrates in fixed position relative to each other by a holding fixture.

4) (Previously Presented) The process of **claim 1**, further comprising testing the connection between the first and second circuit patterns prior to the step of separating the common circuit board substrate into separate substrates.

5) (Previously Presented) The process of **claim 1**, wherein the step of separating occurs after the step of fastening.

6) (Canceled).

7) (Previously Presented) The process of **claim 1**, wherein:

(a) the common circuit board substrate comprises at least a first substrate section and a second substrate section;

(b) the step of forming comprises forming a plurality of circuit patterns on the first substrate section and a plurality of circuit patterns on the second substrate section; and

(c) the step of fastening further comprises making a plurality of connections between circuit patterns on the first substrate section and the second substrate section.

8) (Amended) The process of **claim 1**, wherein the step of separating further comprises pressing the common circuit board substrate along a dividing line until it separates into at least the first and second substrates.

9) (Amended) The process of **claim 1**, wherein the step of separating further comprises cutting the common circuit board substrate into a plurality of separate substrates.

10) Canceled.

11) (Previously Presented) The process of **claim 1**, wherein the at least one electrically conductive wire comprises a pre-insulated wire.

12) Canceled.

13) Canceled.

14) (Original) The process of **claim 3**, wherein the step of holding further comprises using a holding fixture for holding at least one of the separated substrates at a non-planar angle in respect to another separated substrate.

15) (Original) The process of **claim 3**, wherein the step of holding further comprises holding at least one of the separated substrates in proximity to a frame member of an assembly that includes at least one of the separated substrates.

16) (Original) The process of **claim 15**, wherein one separated substrate is held in proximity to one frame member and at least another separated substrate is held in proximity to a second frame member.

17) (Original) The process of **claim 15**, wherein the frame member is a sidewall of a cabinet for housing the assembly that contains at least one of the separated substrates.

18) (Original) The process of **claim 2**, wherein the step of scoring comprises forming a groove in the common substrate, said groove having sides angled at less than 60 degrees.

19) (Previously Presented) The process of **claim 1**, wherein the step of separating further comprises using an edged tool placed in contact with the common circuit board substrate along a dividing line.

20) (Previously Presented) The process of **claim 3**, wherein the step of fastening further comprises connecting at least one electrically conductive pre-formed wire externally from the holding fixture.

21) (Cancelled)

22) (Previously Presented) The process of **claim 1**, wherein the step of fastening further comprises attaching flexible ribbon wires.

23) (Cancelled)

24) (Previously Presented) The process of **claim 1**, wherein the step of fastening comprises an inserting process.

25) (Previously Presented) The process of **claim 1**, wherein the step of fastening comprises a soldering process.
